Edward F. (Ted) Smith, FCSI, FAIA

"In view of your manifest talent and profound impact on the automation and improvement of construction specifications; for your enhancement of architectural education; for your vision and leadership in the international construction community; and for your tireless work ethic and unwavering commitment and dedication to the principles of your profession, you are advanced to Fellowship in the Institute on the 6th day of June 2008"

Las Vegas, Nevada



EDWARD F. SMITH graduated Cum Laude with a Bachelor of Fine Arts and a Bachelor of Architecture, from the University of Utah. He holds a Diplome D'Architecture from the Ecoles D'Art Americaines in Fountainbleau, France. His post-graduate work includes a Master of Science Degree in Computer Science from the University of Utah and a Doctor of Architecture from The University of Michigan. He is a Fellow of The American Institute of Architects and the Construction Specifications Institute.

For more than 30 years, Ted has been a practicing architect, a professor of architecture in the Graduate School of Architecture, University of Utah, and a recognized leader in developing computer applications for architectural practice. As a Professor of Architecture, Ted's focus was on the use of computers, computer graphics, and computer-aided-design in architecture.

Smith pioneered computer research at the Graduate School of Architecture, taught a variety of early computer applications for architectural practice, developed the computing curriculum in architecture, and formulated an optional computing-in-architecture degree program. He established a visiting scholar and student exchange program with the Kajima Corporation of Tokyo; and developed computer-aided architectural education software while at The University of Michigan. Ted is currently a Professor Emeritus of Architecture.

His combined credentials in architecture and computer science led to the founding of Architectural Computer Services, Inc. (ARCOM) in 1987. This corporation is dedicated to developing master specifications and computer tools to automate specification production. ARCOM has been the publisher of the MASTERSPEC Specification System for the AIA since 1995.

Ted served as President and Chairman of ARCOM from its incorporation in 1987 to his retirement in 2006. He is now Chairman Emeritus of ARCOM.

Ted's ARCOM responsibilities as President of ARCOM included general management of the corporation; new business and product development; liaisons with the AIA and CSI as well as with professional organizations that endorse MASTERSPEC, the MASTERSPEC Review Committees, and MASTERSPEC Users.

Smith signed a number of endorsements and strategic alliances with national design-related professional organizations and associations to advance wider MASTERSPEC exposure and increased use of master guide specifications.

Specification products developed by ARCOM under Ted's direction included MASTERSPEC SMALL PROJECTTM, MASTERSPEC OUTLINETM, MASTERSPEC Landscape Architecture, MASTERSPEC Interior Design, PRODUCT MASTERSPECTM, and Specifying LEED Requirements in MASTERSPEC. Software Development included the SPECWARE® family of specification enhancement software, including MASTERWORKSTM and the LINXTM Automated Specification Editing software.

Smith oversaw the integration of environmental and sustainability specification requirements in MASTERSPEC with particular emphasis on USGBC's LEED rating system.

Ted has been a regular presenter at CSI and AIA chapters, CSI regional conventions, CSI, AIA, ASLA, ACEC, and NSPE national conventions, and ICIS delegate assemblies. He has served on several national CSI, AIA, and NIBS committees and is currently Chair of the CSI OmniClass Development Committee.

CSI Membership

Salt Lake City Chapter, 1992

Institute Offices, Committees

Formats Committee, FY 1992-1993 OmniClass Task Team, FY 2000-2006 MasterFormat Expansion Task Team, FY 2001-2004 OmniClass Development Committee Chair, FY 2008-Present

Awards

President's Plaque, 1998 Advancement of Construction Technology Award, 2002 Outstanding Exhibitor Award, 2003 President's Plaque, 2006